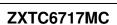




A Product Line of Diodes Incorporated



COMPLEMENTARY 15V NPN & 12V PNP LOW SATURATION TRANSISTOR

Features

NPN Transistor

- BV_{CEO} > 15V
 - I_C = 4.5A Continuous Collector Current
 - Low Saturation Voltage (100mV max @ 1A)
 - $R_{SAT} = 45m\Omega$ for a low equivalent On-Resistance

PNP Transistor

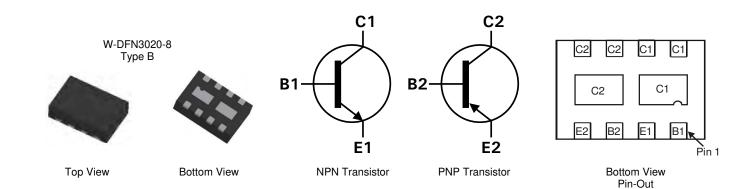
- BV_{CEO} > -12V
- I_C = -4A Continuous Collector Current
- Low Saturation Voltage (-140mV max @ -1A)
- $R_{SAT} = 60m\Omega$ for a low equivalent On-Resistance
- here characterized up to 12A for high current gain hold up
- Low profile 0.8mm high package for thin applications
- R_{0JA} efficient, 40% lower than SOT26
- 6mm² footprint, 50% smaller than TSOP6 and SOT26
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP capable (Note 4)

Mechanical Data

- Case: W-DFN3020-8 Type B
- Nominal package height: 0.8mm
- Case material: molded plastic. "Green" molding compound.
- UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu, Solderable per MIL-STD-202, Method 208 @4
- Weight: 0.013 grams (approximate)

Applications

- DC DC Converters
- Charging circuits
- Power switches
- Motor control
- LED Backlighting circuits
- Portable applications



Ordering Information (Note 4 & 5)

Product	Compliance	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
ZXTC6717MCTA	AEC-Q101	DA1	7	8	3,000
ZXTC6717MCQTA	Automotive	DA1	7	8	3,000

Notes:

1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.

See http://www.diodes.com for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified.

5. For packaging details, go to our website at http://www.diodes.com

Marking Information



DA1 = Product type Marking Code Dot denotes Pin 1



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	NPN	PNP	Unit
Collector-Base Voltage		V _{CBO}	40	-20	V
Collector-Emitter Voltage		V _{CEO}	15	-12	V
Emitter-Base Voltage		V _{EBO}	7	-7	V
Peak Pulse Current		I _{CM}	15	-12	А
Continuous Collector Current	(Notes 6 & 9)	- I _C	4.5	-4	^
Continuous Collector Current	(Notes 7 & 9)		5	-4.45	A
Base Current		IB	1		A

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	NPN	PNP	Unit	
	(Notes 6 & 9)		1.5 12 2.45 19.6 1.13 8 1.7 13.6		W mW/°C
Power Dissipation	(Notes 7 & 9)	5			
Linear Derating Factor	(Notes 8 & 9)	PD			
	(Notes 8 & 10)				
	(Notes 6 & 9)		83.3 51.0		_
Thermal Desistance, hunsting to Ambient	(Notes 7 & 9)				
Thermal Resistance, Junction to Ambient	(Notes 8 & 9)	$R_{ extsf{ heta}JA}$	11	1	°C/W
	(Notes 8 & 10)		73.5		
Thermal Resistance, Junction to Lead	(Notes 9 & 11)	$R_{\theta JL}$	17	.1	7
Operating and Storage Temperature Range	TJ, TSTG	-55 to	+150	°C	

6. For a dual device surface mounted on 28mm x 28mm (8cm²) FR4 PCB with high coverage of single sided 2 oz copper, in still air conditions; the device is Notes: measured when operating in a steady-state condition. The heatsink is split in half with the exposed collector pads connected to each half. 7. Same as note (6), except the device is measured at t <5 sec. 8. Same as note (6), except the device is surface mounted on 31mm x 31mm (10cm²) FR4 PCB with high coverage of single sided 1oz copper.

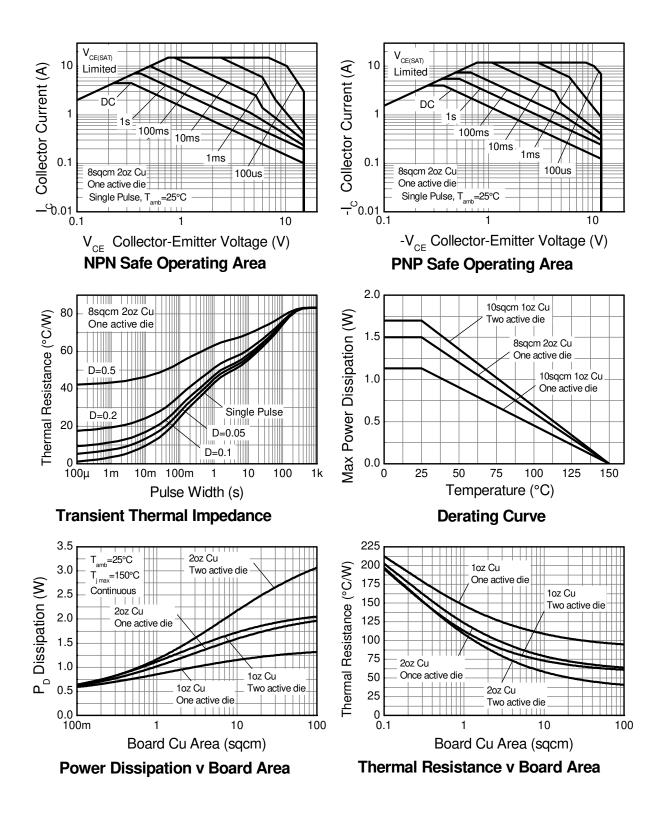
9. For a dual device with one active die.

For dual device with 2 active die running at equal power.
Thermal resistance from junction to solder-point (on the exposed collector pads).





Thermal Characteristics and Derating Information





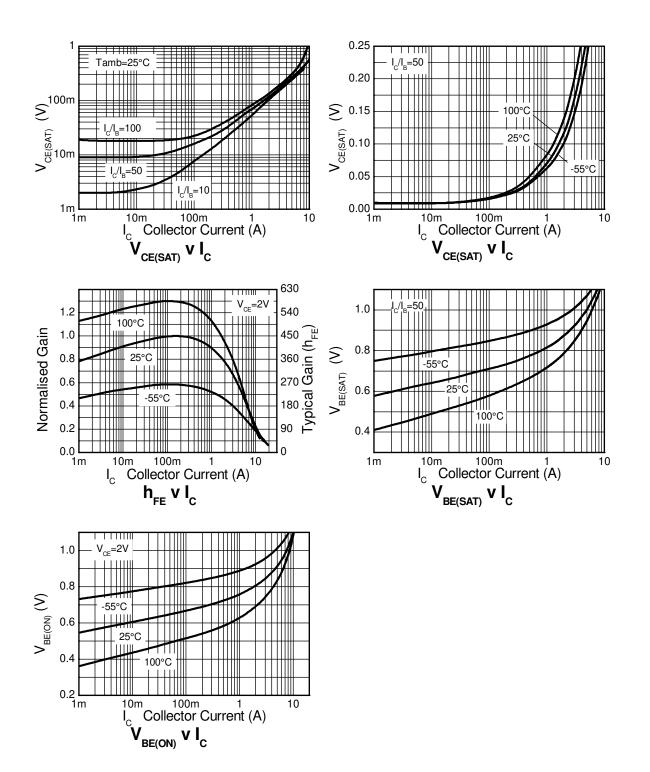
NPN - Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

						-
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV _{CBO}	40	70	-	V	$I_{C} = 100 \mu A$
Collector-Emitter Breakdown Voltage (Note 12)	BV _{CEO}	15	18	-	V	$I_{\rm C} = 10 {\rm mA}$
Emitter-Base Breakdown Voltage	BV _{EBO}	7	8.2	-	V	I _E = 100μA
Collector Cutoff Current	I _{CBO}	-	-	100	nA	$V_{CB} = 30V$
Emitter Cutoff Current	I _{EBO}	-	-	100	_ nA	$V_{EB} = 6V$
Collector Emitter Cutoff Current	I _{CES}	-	-	100	nA	$V_{CE} = 12V$
Static Forward Current Transfer Ratio (Note 12)	hfe	200 300 200 150	415 450 320 240 80	- - - -	-	$\begin{split} I_{C} &= 10 \text{mA}, \ V_{CE} = 2 \text{V} \\ I_{C} &= 200 \text{mA}, \ V_{CE} = 2 \text{V} \\ I_{C} &= 3 \text{A}, \ V_{CE} = 2 \text{V} \\ I_{C} &= 5 \text{A}, \ V_{CE} = 2 \text{V} \\ I_{C} &= 12 \text{A}, \ V_{CE} = 2 \text{V} \end{split}$
Collector-Emitter Saturation Voltage (Note 12)	V _{CE(sat)}	-	8 70 165 240 200	14 100 200 310 -	mV	$ \begin{split} I_C &= 0.1A, \ I_B = 10mA \\ I_C &= 1A, \ I_B = 10mA \\ I_C &= 3A, \ I_B = 50mA \\ I_C &= 4.5A, \ I_B = 50mA \\ I_C &= 4.5A, \ I_B = 100mA \end{split} $
Base-Emitter Turn-On Voltage (Note 12)	V _{BE(on)}	-	0.88	0.96	V	$I_{C} = 4.5A, V_{CE} = 2V$
Base-Emitter Saturation Voltage (Note 12)	V _{BE(sat)}	-	0.94	1.05	V	I _C = 4.5A, I _B = 50mA
Output Capacitance	Cobo	-	30	40	pF	V _{CB} = 10V. f = 1MHz
Transition Frequency	f _T	80	120	-	MHz	$V_{CE} = 10V, I_{C} = 50mA,$ f = 100MHz
Turn-on Time	t _{on}	-	120	-	ns	$V_{CC} = 10V, I_{C} = 1A$
Turn-off Time	t _{off}	-	160	-	ns	$I_{B1} = I_{B2} = 10 \text{mA}$

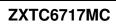
Notes: 12. Measured under pulsed conditions. Pulse width $\leq 300 \mu s.$ Duty cycle $\leq~2\%.$



NPN – Typical Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)







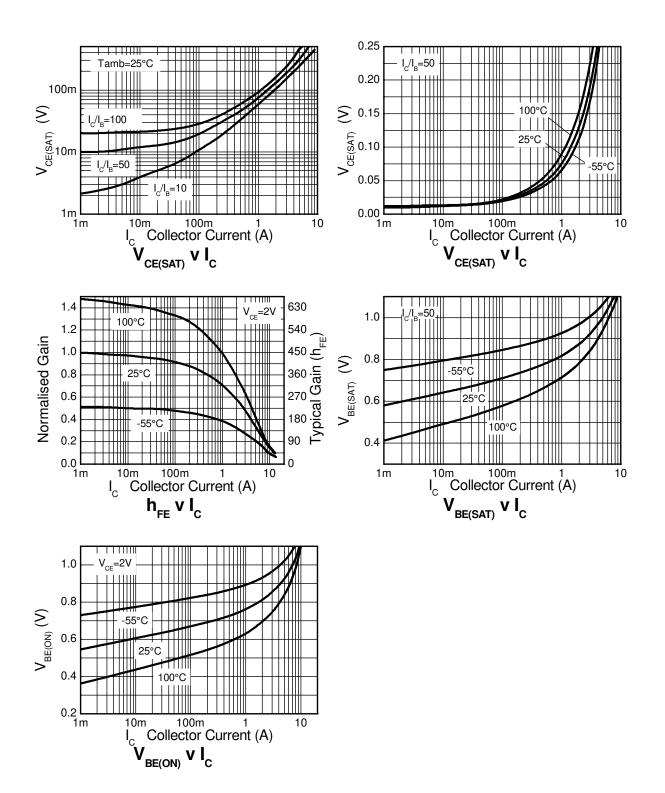
PNP - Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV _{CBO}	-20	-35	-	V	I _C = -100μA
Collector-Emitter Breakdown Voltage (Note 12)	BV _{CEO}	-12	-25	-	V	I _C = -10mA
Emitter-Base Breakdown Voltage	BV _{EBO}	-7	-8.5	-	V	I _E = -100μA
Collector Cutoff Current	Iсво	-	-	-100	nA	V _{CB} = -16V
Emitter Cutoff Current	I _{EBO}	-	-	-100	_ nA	$V_{EB} = -6V$
Collector Emitter Cutoff Current	I _{CES}	-	-	-100	nA	V _{CES} = -10V
Static Forward Current Transfer Ratio (Note 12)	hfe	300 300 180 60 45	475 450 275 100 70	- - -	-	$\begin{split} I_{C} &= -10 \text{mA}, \ V_{CE} &= -2 \text{V} \\ I_{C} &= -100 \text{mA}, \ V_{CE} &= -2 \text{V} \\ I_{C} &= -2.5 \text{A}, \ V_{CE} &= -2 \text{V} \\ I_{C} &= -8 \text{A}, \ V_{CE} &= -2 \text{V} \\ I_{C} &= -10 \text{A}, \ V_{CE} &= -2 \text{V} \end{split}$
Collector-Emitter Saturation Voltage (Note 12)	V _{CE(sat)}		-10 -100 -100 -195 -240	-17 -140 -150 -300 -310	mV	$\begin{split} I_{C} &= -0.1A, \ I_{B} &= -10mA \\ I_{C} &= -1A, \ I_{B} &= -10mA \\ I_{C} &= -1.5A, \ I_{B} &= -50mA \\ I_{C} &= -3A, \ I_{B} &= -50mA \\ I_{C} &= -4A, \ I_{B} &= -150mA \end{split}$
Base-Emitter Turn-On Voltage (Note 12)	V _{BE(on)}	-	-0.87	-0.96	V	$I_{C} = -4A, V_{CE} = -2V$
Base-Emitter Saturation Voltage (Note 12)	V _{BE(sat)}	-	-0.97	-1.07	V	$I_{C} = -4A, I_{B} = -150mA$
Output Capacitance	Cobo	-	21	30	pF	V _{CB} = -10V. f = 1MHz
Transition Frequency	f _T	100	110	-	MHz	$V_{CE} = -10V, I_C = -50mA, f = 100MHz$
Turn-on Time	t _{on}	-	70	-	ns	$V_{CC} = -6V, I_{C} = -2A$
Turn-off Time	t _{off}	-	130	-	ns	$I_{B1} = I_{B2} = -50 \text{mA}$

Notes: 12. Measured under pulsed conditions. Pulse width \leq 300µs. Duty cycle \leq 2%.



PNP – Typical Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

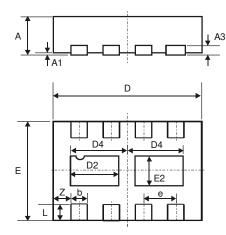






Package Outline Dimensions

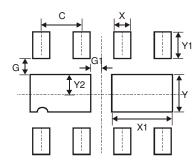
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



W-DFN3020-8 Type B					
Dim	m Min Max Ty				
Α	0.77	0.83	0.80		
A1	0	0.05	0.02		
A3	-	-	0.15		
b	0.25	0.35	0.30		
D	2.95	3.075	3.00		
D2	0.82	1.02	0.92		
D4	1.01	1.21	1.11		
e	-	-	0.65		
Е	1.95	2.075	2.00		
E2	0.43	0.63	0.53		
L	0.25	0.35	0.30		
Ζ	-	-	0.375		
All Dimensions in mm					

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	0.650
G	0.285
G1	0.090
Х	0.400
X1	1.120
Y	0.730
Y1	0.500
Y2	0.365



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